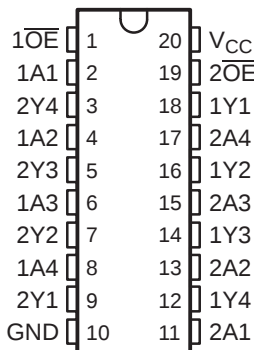


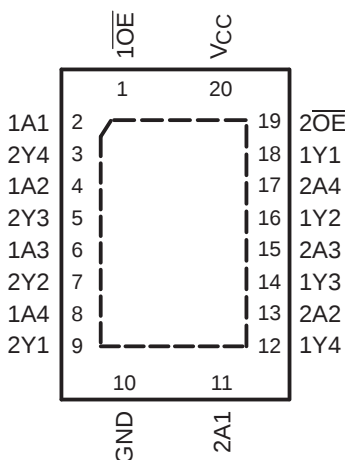
FEATURES

- Operate From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 5.9 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Support Mixed-Mode Signal Operation on All Ports
(5-V Input/Output Voltage With 3.3-V V_{CC})
- I_{off} Supports Partial-Power-Down Mode Operation
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

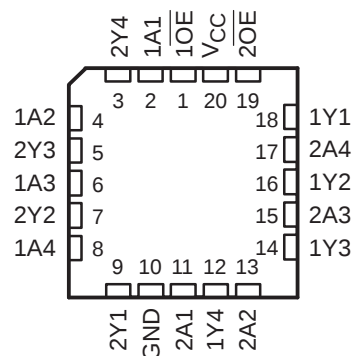
SN54LVCH244A . . . J OR W PACKAGE
SN74LVCH244A . . . DB, DBQ, DGV, DW,
NS, OR PW PACKAGE
(TOP VIEW)



SN74LVCH244A . . . RGY PACKAGE
(TOP VIEW)



SN54LVCH244A . . . FK PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The SN54LVCH244A octal buffer/line driver is designed for 2.7-V to 3.6-V V_{CC} operation, and the SN74LVCH244A octal buffer/line driver is designed for 1.65-V to 3.6-V V_{CC} operation.

These devices are organized as two 4-bit line drivers with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, these devices pass data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN54LVCH244A, SN74LVCH244A

OCTAL BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

SCES0090–JULY 1995–REVISED FEBRUARY 2007

ORDERING INFORMATION

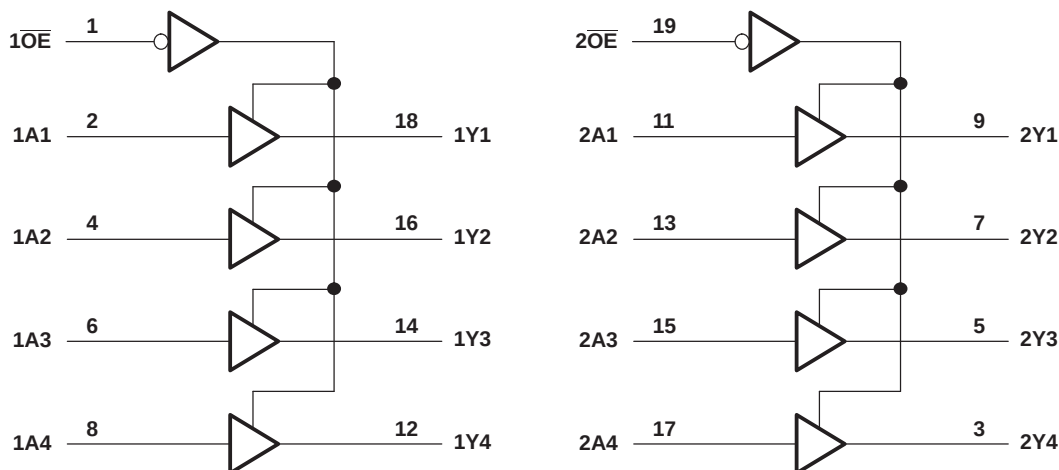
T _A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Reel of 1000	SN74LVCH244ARGYR	LCH244A
	SOIC – DW	Tube of 25	SN74LVCH244ADW	LVCH244A
		Reel of 2000	SN74LVCH244ADWR	
	SOP – NS	Reel of 2000	SN74LVCH244ANSR	LVCH244A
	SSOP – DB	Reel of 2000	SN74LVCH244ADBR	LCH244A
	SSOP (QSOP) – DBQ	Reel of 2500	SN74LVCH244ADBQR	LVCH244A
	TSSOP – PW	Tube of 70	SN74LVCH244APW	LCH244A
		Reel of 2000	SN74LVCH244APWR	
		Reel of 250	SN74LVCH244APWT	
	TVSOP – DGV	Reel of 2000	SN74LVCH244ADGVR	LCH244A
–55°C to 125°C	CDIP – J	Tube of 20	SNJ54LVCH244AJ	SNJ54LVCH244AJ
	CFP – W	Tube of 85	SNJ54LVCH244AW	SNJ54LVCH244AW
	LCCC – FK	Tube of 55	SNJ54LVCH244AFK	SNJ54LVCH244AFK

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (EACH BUFFER)

INPUTS		OUTPUT Y
$\overline{OE}$	A	
L	H	H
L	L	L
H	X	Z

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	–0.5	6.5	V
V_I	Input voltage range ⁽²⁾	–0.5	6.5	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	–0.5	6.5	V
V_O	Voltage range applied to any output in the high or low state ⁽²⁾⁽³⁾	–0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$		–50 mA
I_{OK}	Output clamp current	$V_O < 0$		–50 mA
I_O	Continuous output current		±50	mA
	Continuous current through V_{CC} or GND		±100	mA
θ_{JA}	Package thermal impedance	DB package ⁽⁴⁾	70	°C/W
		DBQ package ⁽⁴⁾	68	
		DGV package ⁽⁴⁾	92	
		DW package ⁽⁴⁾	58	
		NS package ⁽⁴⁾	60	
		PW package ⁽⁴⁾	83	
		RGY package ⁽⁵⁾	37	
T_{stg}	Storage temperature range	–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The value of V_{CC} is provided in the recommended operating conditions table.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

(5) The package thermal impedance is calculated in accordance with JESD 51-5.

SN54LVCH244A, SN74LVCH244A

OCTAL BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

SCES0090–JULY 1995–REVISED FEBRUARY 2007

Recommended Operating Conditions⁽¹⁾

			SN54LVCH244A		SN74LVCH244A		UNIT
			MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	Operating	2	3.6	1.65	3.6	V
		Data retention only	1.5		1.5		
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V			0.65 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V			1.7		
		V _{CC} = 2.7 V to 3.6 V	2		2		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V			0.35 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V			0.7		
		V _{CC} = 2.7 V to 3.6 V		0.8	0.8		
V _I	Input voltage		0	5.5	0	5.5	V
V _O	Output voltage	High or low state	0	V _{CC}	0	V _{CC}	V
		3-state	0	5.5	0	5.5	
I _{OH}	High-level output current	V _{CC} = 1.65 V				–4	mA
		V _{CC} = 2.3 V				–8	
		V _{CC} = 2.7 V		–12		–12	
		V _{CC} = 3 V		–24		–24	
I _{OL}	Low-level output current	V _{CC} = 1.65 V				4	mA
		V _{CC} = 2.3 V				8	
		V _{CC} = 2.7 V		12		12	
		V _{CC} = 3 V		24		24	
Δt/Δv	Input transition rise or fall rate			10		10	ns/V
T _A	Operating free-air temperature		–55	125	–40	85	°C

(1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	SN54LVCH244A		SN74LVCH244A		UNIT	
				MIN	TYP ⁽¹⁾ MAX	MIN	TYP ⁽¹⁾ MAX		
V _{OH}	I _{OH} = –100 μA		1.65 V to 3.6 V			V _{CC} – 0.2		V	
			2.7 V to 3.6 V	V _{CC} – 0.2					
	I _{OH} = –4 mA		1.65 V		1.2				
	I _{OH} = –8 mA		2.3 V		1.7				
	I _{OH} = –12 mA		2.7 V		2.2				
			3 V		2.4				
I _{OH} = –24 mA		3 V		2.2		2.2			
V _{OL}	I _{OL} = 100 μA		1.65 V to 3.6 V			0.2		V	
			2.7 V to 3.6 V	0.2					
	I _{OL} = 4 mA		1.65 V		0.45				
	I _{OL} = 8 mA		2.3 V		0.7				
	I _{OL} = 12 mA		2.7 V		0.4				
	I _{OL} = 24 mA		3 V		0.55				
I _I	V _I = 0 to 5.5 V		3.6 V		±5		±5		μA
I _{off}	V _I or V _O = 5.5 V		0				±10		μA
I _{I(hold)}	V _I = 0.58 V		1.65 V			(2)		μA	
	V _I = 1.07 V					(2)			
	V _I = 0.7 V		2.3 V		45				
	V _I = 1.7 V				–45				
	V _I = 0.8 V		3 V	75		75			
	V _I = 2 V			–75		–75			
	V _I = 0 to 3.6 V ⁽³⁾		3.6 V		±500		±500		
I _{OZ}	V _O = 0 to 5.5 V		3.6 V		±15		±10		μA
I _{CC}	V _I = V _{CC} or GND		3.6 V	10		10		μA	
	3.6 V ≤ V _I ≤ 5.5 V ⁽⁴⁾			10		10			
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND		2.7 V to 3.6 V		500		500		μA
C _i	V _I = V _{CC} or GND		3.3 V		4 12		4		pF
C _o	V _O = V _{CC} or GND		3.3 V		5.5 12		5.5		pF

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

(2) This information was not available at the time of publication.

(3) This is the bus-hold maximum dynamic current required to switch the input from one state to another.

(4) This applies in the disabled state only.

SN54LVCH244A, SN74LVCH244A

OCTAL BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

SCES0090 – JULY 1995 – REVISED FEBRUARY 2007

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVCH244A			UNIT	
			V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		
			MIN	MAX	MIN		MAX
t _{pd}	A	Y	7.5		1	6.5	ns
t _{en}	$\overline{OE}$	Y	9		1	8	ns
t _{dis}	$\overline{OE}$	Y	8		1	7	ns

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74LVCH244A								UNIT
			V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Y	(1)	(1)	(1)	(1)	6.9	1.5	5.9	ns	
t _{en}	$\overline{OE}$	Y	(1)	(1)	(1)	(1)	8.6	1	7.6	ns	
t _{dis}	$\overline{OE}$	Y	(1)	(1)	(1)	(1)	6.8	1.5	5.8	ns	

(1) This information was not available at the time of publication.

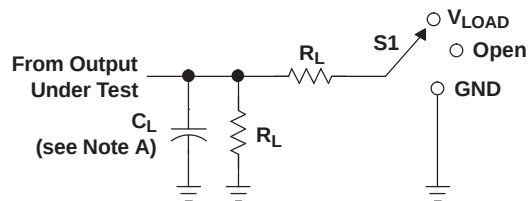
Operating Characteristics

T_A = 25°C

PARAMETER			TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT
				TYP	TYP	TYP	
C _{pd}	Power dissipation capacitance per buffer/driver	Outputs enabled	f = 10 MHz	(1)	(1)	47	pF
		Outputs disabled		(1)	(1)	2	

(1) This information was not available at the time of publication.

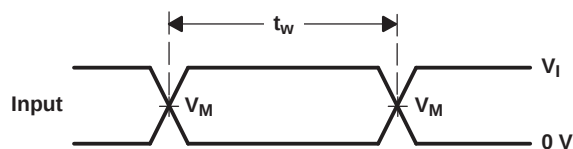
PARAMETER MEASUREMENT INFORMATION



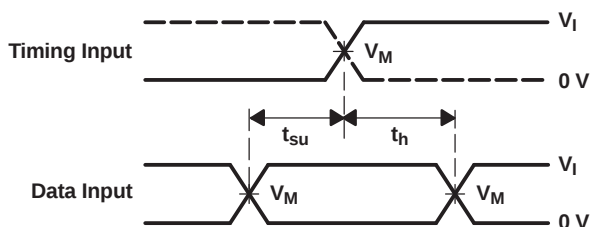
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

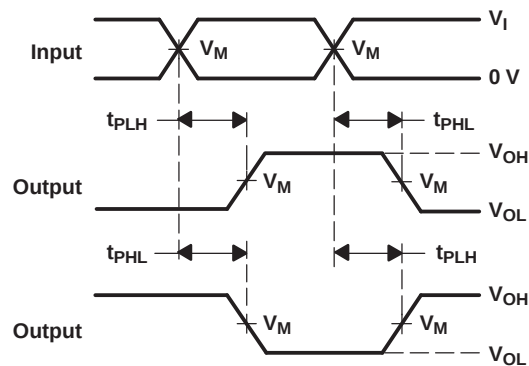
V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8\text{ V} \pm 0.15\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V



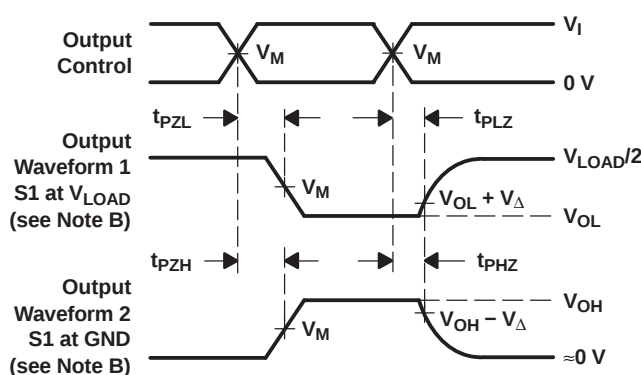
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9754201Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9754201QRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9754201QSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
5962-9754201V2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9754201VRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9754201VSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
SN74LVCH244ADBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74LVCH244ADBQR	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74LVCH244ADBQRE4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74LVCH244ADBQRG4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74LVCH244ADBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ADBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ADBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ADGVR	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ADGVRE4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ADGVRG4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244APWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244APWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
no Sb/Br)								
SN74LVCH244APWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74LVCH244APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244APWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244APWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244APWT	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244APWTE4	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244APWTG4	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH244ARGYR	ACTIVE	QFN	RGY	20	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74LVCH244ARGYRG4	ACTIVE	QFN	RGY	20	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SNJ54LVCH244AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LVCH244AJ	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LVCH244AW	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

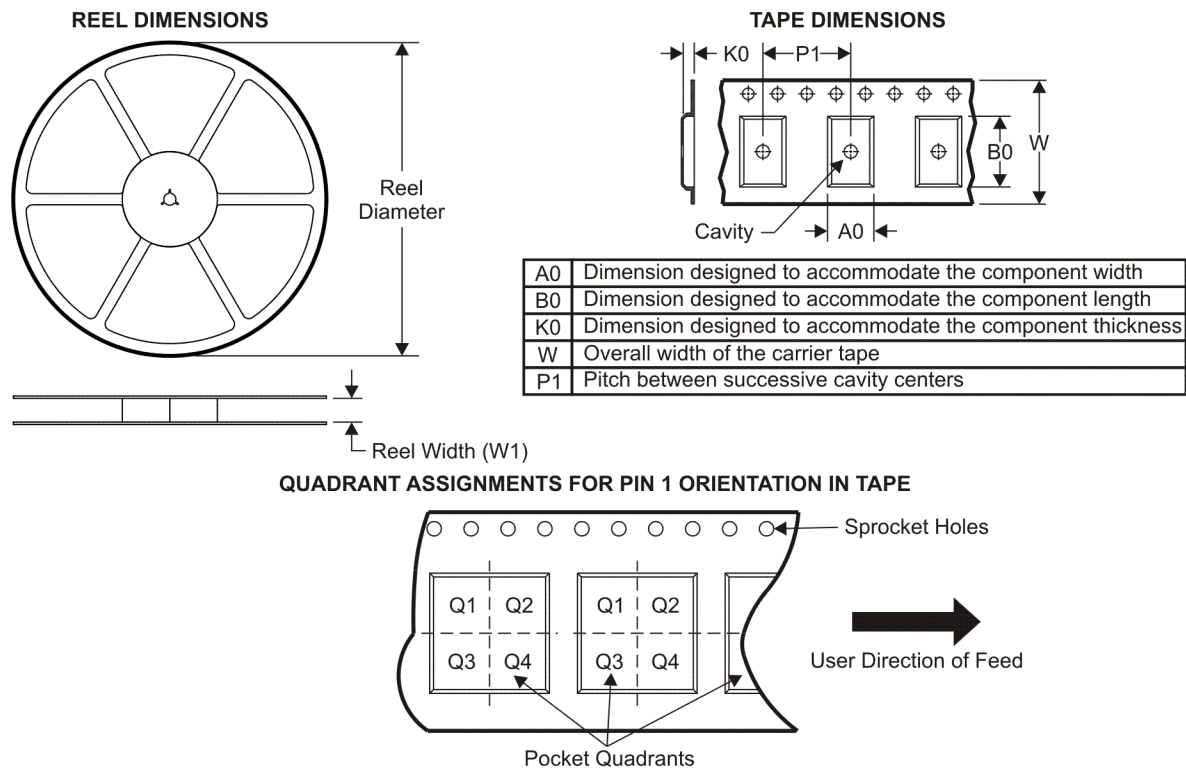
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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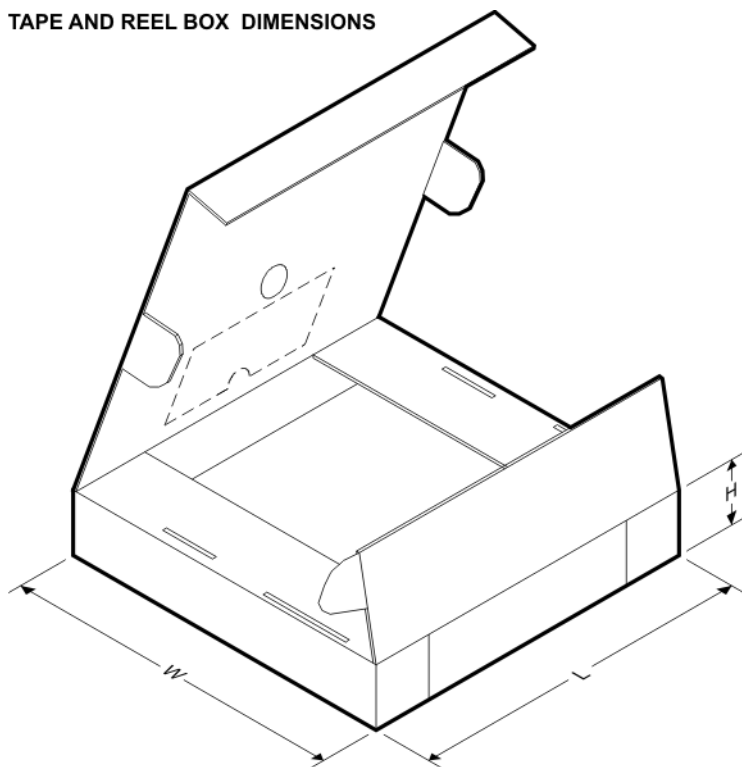
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVCH244ADBQR	SSOP/ QSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVCH244ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LVCH244ADGVR	TVSOP	DGV	20	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74LVCH244ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74LVCH244APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74LVCH244ARGYR	QFN	RGY	20	1000	180.0	12.4	3.8	4.8	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVCH244ADBQR	SSOP/QSOP	DBQ	20	2500	346.0	346.0	33.0
SN74LVCH244ADBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74LVCH244ADGVR	TVSOP	DGV	20	2000	346.0	346.0	29.0
SN74LVCH244ADWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74LVCH244APWR	TSSOP	PW	20	2000	346.0	346.0	33.0
SN74LVCH244ARGYR	QFN	RGY	20	1000	190.5	212.7	31.8

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

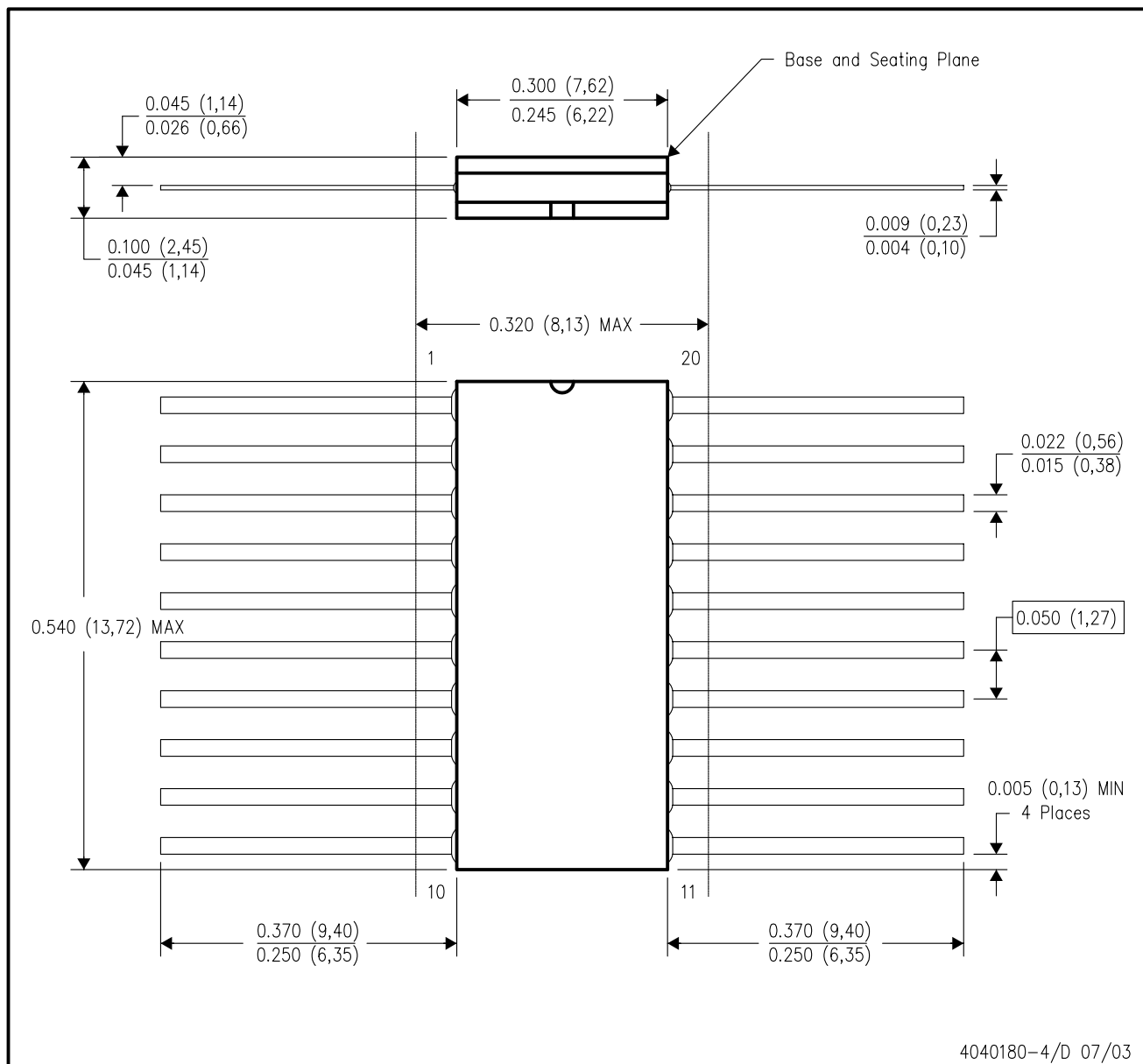
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

W (R-GDFP-F20)

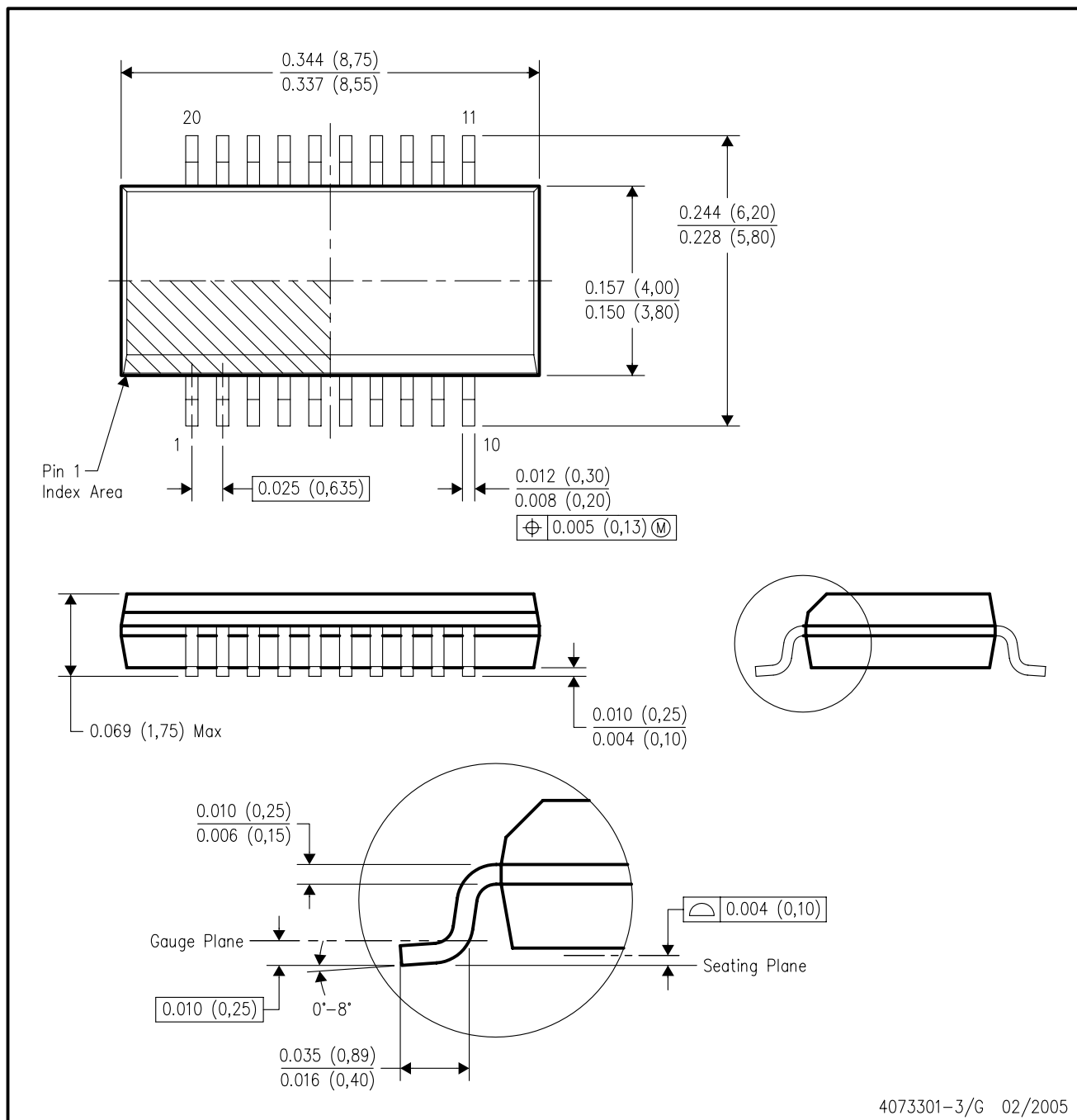
CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within Mil-Std 1835 GDFP2-F20

DBQ (R-PDSO-G20)

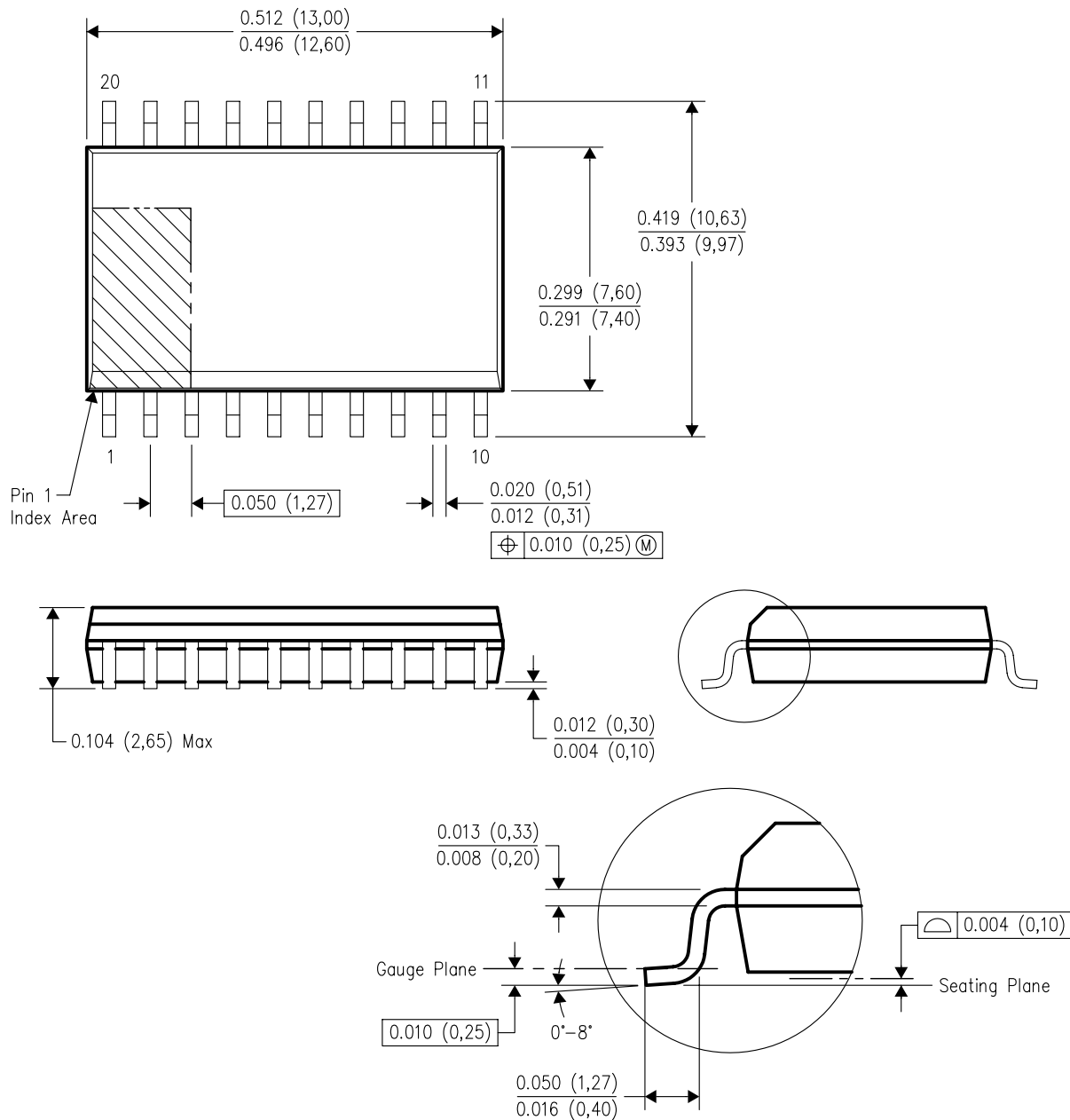
PLASTIC SMALL-OUTLINE PACKAGE



4073301-3/G 02/2005

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE

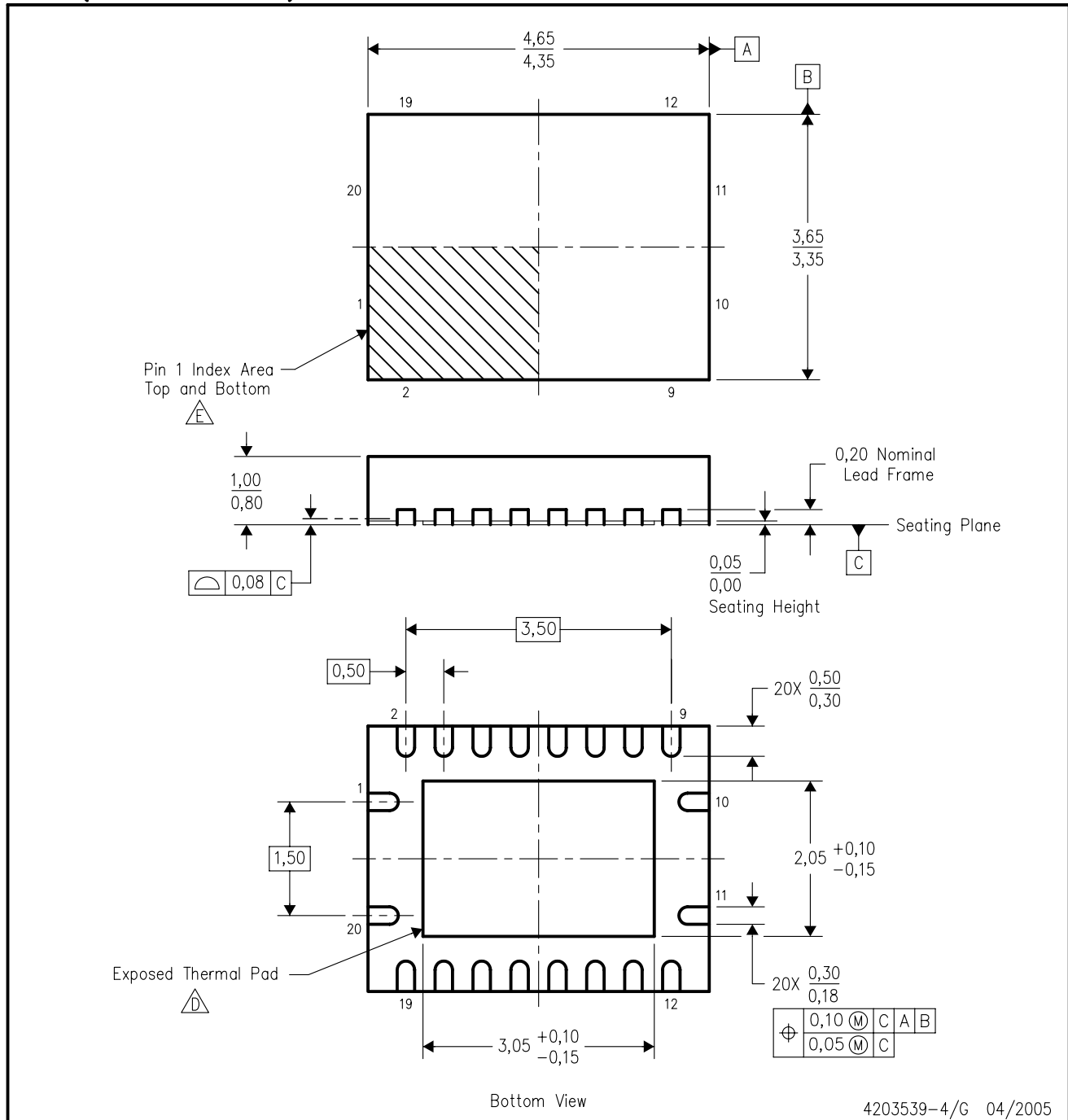


4040000-4/F 06/2004

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

RGY (R-PQFP-N20)

PLASTIC QUAD FLATPACK



4203539-4/G 04/2005

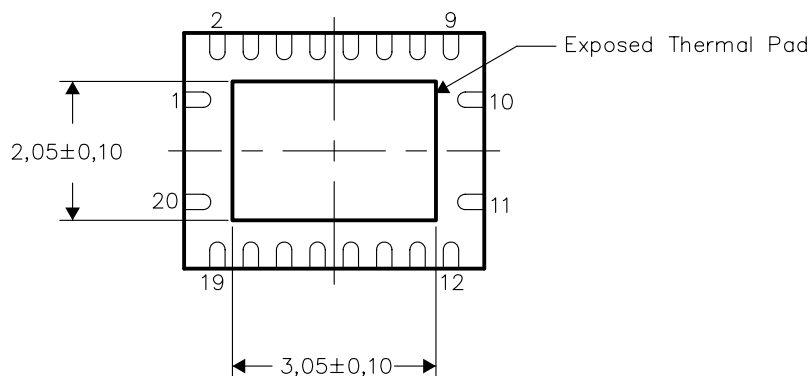
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - F. Package complies to JEDEC MO-241 variation BC.

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, Quad Flatpack No-Lead Logic Packages, Texas Instruments Literature No. SCBA017. This document is available at www.ti.com.

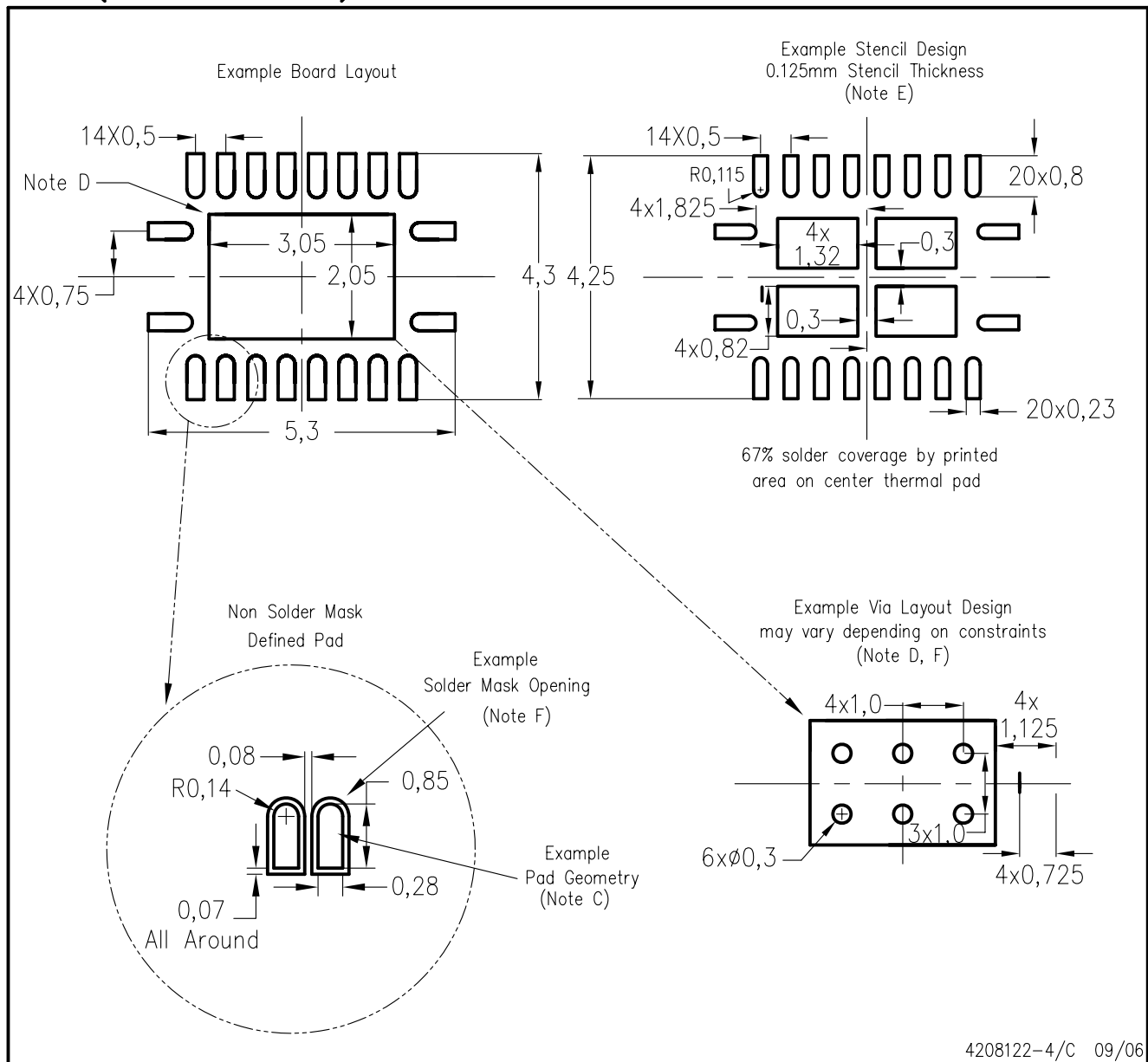
The exposed thermal pad dimensions for this package are shown in the following illustration.



NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

RGY (R-PQFP-N20)



4208122-4/C 09/06

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SCBA017, SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

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